

Build Up HDI (Standard)	
HDI12_1+10b+1_1,25_17.5_engl	12 - Layers Core: 0,10 mm Cu 17.5/17.5 µm
WE-Article No.:	1 + 10B + 1
Customer:	



layer description		configuration	Raw-Material	CU	PREPREG	Final Thickness	Customer requirements	
Customer	WE					[µm]	[µm]	
	TOP/VS		Foil	12 µm ¹⁾		12		
					1 x 1080	60		
	2			Foil	9 µm		30	
					1 x 1080	66		
	3				17.5 µm		16	
				0,100 mm			100	
	4				17.5 µm		16	
					2 x 1080	134		
	5				17.5 µm		16	
				0,100 mm			100	
	6				17.5 µm		16	
					2 x 1080	134		
	7			17.5 µm		16		
			0,100 mm			100		
	8			17.5 µm		16		
				2 x 1080	134			
	9			17.5 µm		16		
			0,100 mm			100		
	10			17.5 µm		16		
				1 x 1080	66			
	11		Foil	9 µm		30		
				1 x 1080	60			
	BOT/RS		Foil	12 µm ¹⁾		12		

1) copper thickness outer layers: appr. 55 µm					
total material thickness: 1266					
<small>Note: Lamination thickness for Prepregs depending on layout characteristics.</small>					

final lamination thickness:	1,25	+-	0,10	mm			Date:	Engineer:
thickness with electro plated Cu:	1,34	+-	0,13	mm				
total thickness with soldermask	1,40	+-	0,15	mm				
customer requirement		+-		mm	point:			
prepared: on 29.03.2006	by S. Keller	checked: on 04.05.2006	by M.Kress	approved: on 04.05.2006	by R.Schönholz	revision 00	page: 12+	